



PATENT ABSTRACTS OF JAPAN

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FUKUDA TOSHIYUKI**(54) **SEMICONDUCTOR DEVICE AND
MANUFACTURING METHOD THEREFOR**

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(57) Abstract:

PROBLEM TO BE SOLVED: To provide a high speed semiconductor device having a chip laminated structure.

SOLUTION: The chip laminate mounted on a semiconductor device comprises a first semiconductor chip 102 in which a first electrode 101 is provided at the peripheral part of a main surface, and a second semiconductor chip 104 in which, being smaller in area than the first semiconductor chip 102, a second electrode 103 is provided on the main surface. The first semiconductor chip 102 is integrated with the second semiconductor chip 104 by gluing such region on the main surface of the first semiconductor chip 102 except the peripheral part to the surface of the second semiconductor chip 104 which is opposed to the main surface. The first electrode 101 is connected to the second electrode 103 by a first inter-chip wiring 108 formed between the main surface of the first semiconductor chip 102, the side surface of the second semiconductor chip 104, and the main surface of the second semiconductor chip 104.

